

ABSTRACT OF THE DISCLOSURE

A micro grid array semiconductor die package includes a housing defining a cavity for holding at least one semiconductor die, said housing including a plurality of insulative side walls, each of said side walls having a bottom surface and an interior wall including a top surface, and an end plate joined to said side walls; and a plurality of substantially straight conductive leads extending through at least one of said side walls, each of said conductive leads including an internal lead section extending into the cavity from the top surface of the interior wall and a external lead section extending externally from said at least one bottom surface of said side wall.